Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

Texas Instruments
LMH730123/NOPB

For any questions, you can email us directly: sales@integrated-circuit.com



Distributor of Texas Instruments: Excellent Integrated System Limited

Datasheet of LMH730123/NOPB - EVALUATION BOARD

Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL: PER IPC-4101/24

 1A. LAMINATE: HIGH-TEMPERATURE FR4
- 1B
- LAMINATE: HIGH-TEMPERATURE FR4
 FINISHED BOARD: JO202 +/- JO205 INCH OUTSIDE LAYERS, COPPER.
 ALL COPPER LAYERS MUST BE SPACED PER DETAIL "A".
 BOARD THICKNESS IS MEASURED INCLUDING TOP AND BOTTOM SIDES
 FINISHED COPPER. ANY TIN, TIN/LEAD OR GOLD PLATING, SOLDERMASK
 AND SILKSCREEN LEGEND MUST NOT BE INCLUDED IN FINISHED BOARD THICKNESS.
- THE CONDUCTOR PATTERN MUST BE ETCHED USING ARTWORK 880011408-003 REV A SUPPLIED WITHIN FABRICATION FILES' ARCHIVE 885011408-003 REV A OR GREATER.
- ALL CONDUCTOR LAYERS MUST BE REGISTERED WITHIN +/- .005 INCH FROM TRUE POSITION.
- ETCH TOLERANCES:

ALL EXTERNAL LAYERS CONDUCTOR WIDTH MUST BE WITHIN +/- .0015 INCH OR +/- 15% OF GERBER DATA, WHICHEVER IS SMALLER.

- BOARD MUST BE NC DRILLED USING DRILL DATA SUPPLIED.
- DRILL TOLERANCES AND HOLE SIZES ARE FOR FINISHED BOARD: ALL PLATED THROUGH HOLES TO .080 INCH ARE +/- .003 INCH. ALL PLATED THROUGH HOLES OVER .081 INCH ARE +/- .005 INCH. ALL NON-PLATED THROUGH HOLES ARE +/- .005 INCH.
 - ALL HOLES MUST BE REGISTERED WITHIN +/-.003 INCH FROM TRUE POSITION.
- MINIMUM ANNULAR RING MUST BE .002 INCH. 8.
- - ING:
 PER MIL-C-14550, PLATED THROUGH HOLES MUST BE PLATED WITH .0008
 MIN. TO .0015 INCH MAX. THICK COPPER.
 FINISH: IMMERSION GOLD: 2 TO 8 MICROINCHES GOLD OVER 120-240
 MICROINCHES OF ELECTROLESS NICKEL.
- 10. WARP AND TWIST OF FINISHED BOARDS MUST NOT EXCEED .007 INCH PER INCH.

- SOLDERMASK: PER IPC-SM-840

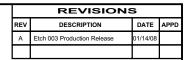
 11A. SOLDERMASK BOTH TOP AND BOTTOM SIDES.

 11B. SOLDERMASK MUST CLEAR ALL LANDS SHOWN ON GERBER SOLDERMASK LAYERS.
- LAYERS.

 11C. COLOR GREEN AND SOLVENT FREE.

 11D. LIQUID PHOTO-IMAGEABLE MUST BE .0002 MIN. TO .0008 MAX. INCH THICK MEASURED OVER COPPER PLATING.

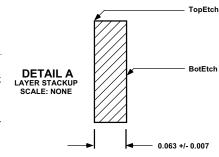
 SILKSCREEN TOP SIDE ONLY USING A GLOSSY WHITE, NONCONDUCTIVE, EPOXY BASED INK. NO SILKSCREEN ALLOWED ON TIN-LEAD OR GOLD AREAS, ON PADS 12 OR IN HOLES.
- ROUTE BOARD OUTLINE, PER DRAWING DIMENSIONS.
 - VENDOR MUST ENTER VENDOR'S IDENTITY, DATE CODE AND ANY OTHER IDENTIFICATION MARKS AS BOTTOM SIDE SOLDERMASK OPENINGS APPROXIMATELY WHERE SHOWN.
- OTHER VENDOR NOMENCLATURE OR MARKINGS SHOULD NOT BE ETCHED OR SILKSCREENED ON BOARD WITHOUT PRIOR PERMISSION. 15
- ALL VENDOR IN-PROCESS MARKINGS, QA STAMPS, ETC. MUST BE PLACED ON THE BOTTOM SIDE OF BOARD. 16.



- FINISHED BOARD MUST MEET UL94V-0 RATING AND RoHS COMPLIANCE.
- DOCUMENTATION THAT MUST BE DELIVERED WITH BOARDS:

 18A. CROSS SECTION REPORT (SPACING BETWEEN COPPER LAYERS AND
 - COPPER THICKNESS)
 ELECTRICAL TEST CERTIFICATION OF COMPLIANCE (ACCORDANCE WITH IPC-ET-652 CLASS II)
 CERTIFICATION OF COMPLIANCE (BOARD HAS BEEN MANUFACTURED TO
 - DRAWING REQUIREMENTS)

 →RoHS CERTIFICATE OF COMPLIANCE



Board Fabrication Information				
	Smallest Feature			
Air Gap	.009 inch			
Trace Width	.016 inch			
Hole Size	.020 inch			
Pad Size	.016 x .040 inch			
Surface Mount	Top side only			

UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE IN INCHES					
SEE NOTES	DRAWN: Ernesto Rey	DATE: 14-Jan-08	National Semiconductor	BOARD & SYSTEM BUSINESS OPERATIONS	
INISH: SEE NOTES	CHECKED:	DATE:		CATION DRAWING	

SEE I Mary Kao В 551011408-003 Α DO NOT COPY, DISPLAY, OR USE DRAWING WITHOUT AUTHORIZATION SHEET 1 OF 2 REV



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